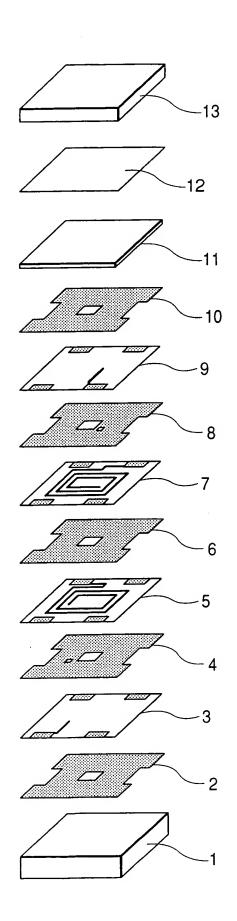


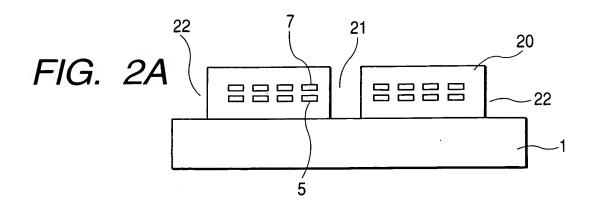
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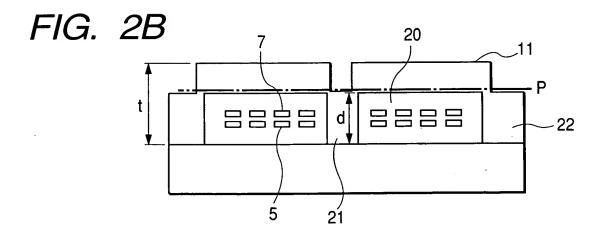
FIG. 1

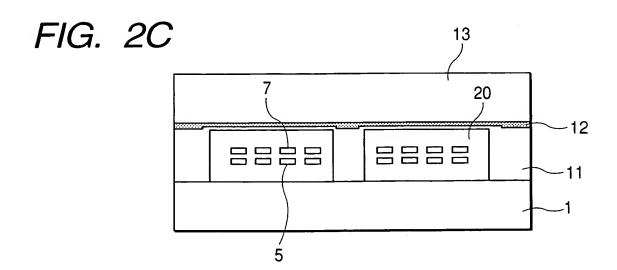


OBLON, SPIVAK, et al Docket No: 249405US3 Inventor: Tomokazu ITO, et al. Serial No: 10/785,029 Reply to NFMP dated: June 17, 2004

Replacement Sheet



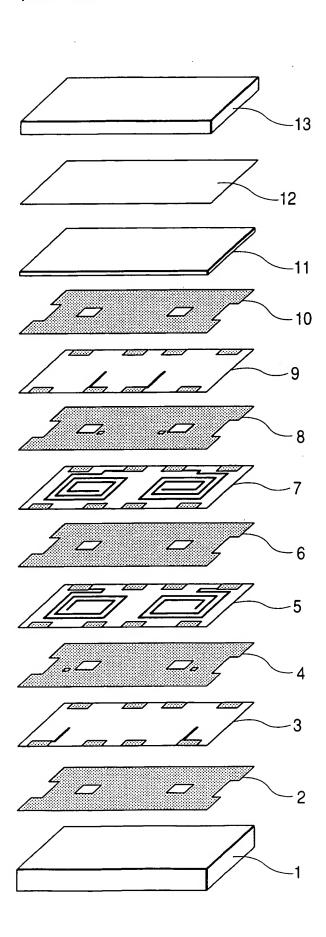




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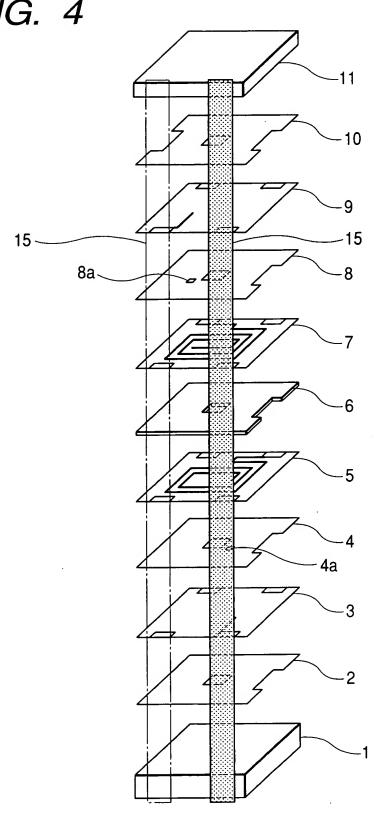
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FIG. 3



OBLON, SPIVAK, et al Docket No: 249405US3 Inventor: Tomokazu ITO, et al. Serial No: 10/785,029 Reply to NFMP dated: June 17, 2004 Replacement Sheet





OBLON, SPIVAK, et al Docket No: 249405US3 Inventor: Tomokazu ITO, et al. Serial No: 10/785,029 Reply to NFMP dated: June 17, 2004 Replacement Sheet

FIG. 5

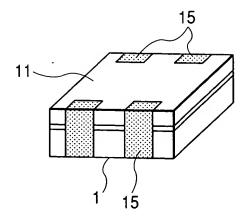
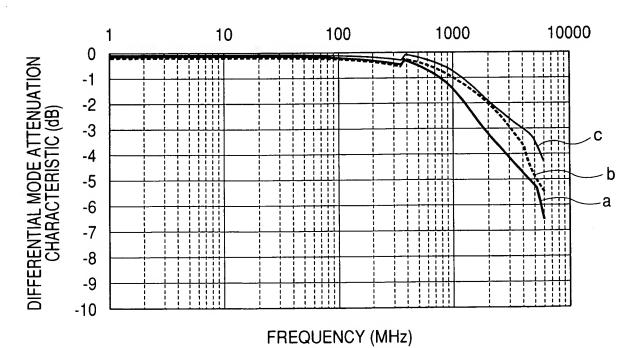


FIG. 6



5,7 ,22 - 22 20 4,6 8 FIG. 7E FIG. 7D REMOVING OF RESIST FIG. 7F **ETCHING OF UNDERCOAT** Ni ELECTROPLATING 22 Ş Ş RESIST COATING/EXPOSURE/DEVELOP 4,6 4,6 4,6 20 FIG. 7A SPUTTERING OF Cr/Cu OR Ti/Cu FIG. 7C FIG. 7B Cu ELECTROPLATING

OBLON, SPIVAK, et al Docket No: 249405US3

Replacement Sheet

Inventor: Tomokazu ITO, et al. Serial No: 10/785,029 Reply to NFMP dated: June 17, 2004 OBLON, SPIVAK, et al Docket No: 249405US3 Inventor: Tomokazu ITO, et al. Serial No: 10/785,029 Reply to NFMP dated: June 17, 2004

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